# XX### REV E1 Bill of Materials

<table>
<thead>
<tr>
<th>Designator</th>
<th>Quantity</th>
<th>Value</th>
<th>PartNumber</th>
<th>Manufacturer</th>
<th>Description</th>
<th>PackageReference</th>
</tr>
</thead>
<tbody>
<tr>
<td>C1</td>
<td>1</td>
<td>560µF</td>
<td>LLG2W561MELB50</td>
<td>Nichicon</td>
<td>CAP, AL, 560 µF, 450 V, +/- 20%, TH</td>
<td>D30xL50mm</td>
</tr>
<tr>
<td>TP1, TP2</td>
<td>2</td>
<td></td>
<td>3620-1-32-15-00-00-08-0</td>
<td>Mill-Max</td>
<td>Edge-Mount Pin, Gold</td>
<td>Edge-Mount Pin</td>
</tr>
</tbody>
</table>
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